

# OL-NX5P2090UK

Wafer level chip-size package; 9 bumps

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	X (other)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	27-3-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.33	-	1.36	1.39	mm
E	package width	1.33	-	1.36	1.39	mm
A	seated height	0.47	-	0.51	0.55	mm
A <sub>2</sub>	package height	0.29	-	0.31	0.34	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	9	-	

## 2. Package outline

Fig. 1. Package outline WLCSP (OL-NX5P2090UK)



### 3. Legal information

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